ON Semiconductor				10/15/2019
Base Part		**FCP600N60Z**	**HF**	
Orderable Part		**FCP600N60Z**	**Total weight (mg)**	**2030.183**
Homogenous Material	**Weight (mg)**	**Substance in Mat.**	**CAS #**	**% Avg. Weight**
Die	2.81	Silicon (Si)	7440-21-3	100
Die Attach Solder	1.111	Silver (Ag)	7440-22-4	2.5
		Lead (Pb)	7439-92-1	92.5
		Tin (Sn)	7440-31-5	5
Lead Frame	1492.122	Nickel (Ni)	7440-02-0	0.01159423
		Iron (Fe)	7439-89-6	0.10052797
		Copper (Cu)	7440-50-8	99.85778643
		Phosphorus (P)	7723-14-0	0.03009137
Mold Compound-Black	518.4	Ortho Cresol Novolac Resin	29690-82-2	10
		Carbon Black (C)	1333-86-4	0.3
		Fused Silica (SiO2)	60676-86-0	79.7
		Phenolic Resin (Novolac)	9003-35-4	10
Plating	13.3	Tin (Sn)	7440-31-5	100
Wire Bond - Al	2.44	Aluminum (Al)	7429-90-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF